

# Ted Hubbard

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/2104305/publications.pdf>

Version: 2024-02-01

11  
papers

151  
citations

1937685

4  
h-index

1588992

8  
g-index

12  
all docs

12  
docs citations

12  
times ranked

127  
citing authors

#	ARTICLE	IF	CITATIONS
1	Heat transfer analysis and optimization of two-beam microelectromechanical thermal actuators. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2002, 20, 971-974.	2.1	110
2	Theoretical and experimental analysis of an off-chip microgripper. Canadian Journal of Electrical and Computer Engineering, 2006, 31, 77-84.	2.0	12
3	Simulation and optical measurement of MEMS thermal actuator sub-micron displacements in air and water. , 2015, , .		9
4	Submicron displacement measurements of MEMS using optical microphotographs in aqueous media: Enhancement using color image processing. Materials Research Society Symposia Proceedings, 2014, 1659, 43-48.	0.1	6
5	Modal Simulation and Testing of a Micro-Manipulator. Journal of Dynamic Systems, Measurement and Control, Transactions of the ASME, 2005, 127, 515-519.	1.6	4
6	MEMS measurements of single cell stiffness decay due to cyclic mechanical loading. Biomedical Microdevices, 2017, 19, 77.	2.8	3
7	Phytolith assaying using a micron-scale electrokinetic sorting ring. Archaeological and Anthropological Sciences, 2011, 3, 309-323.	1.8	2
8	Rehydration of active dried yeast: impact on strength and stiffness of yeast cells measured using microelectromechanical systems. Journal of the Institute of Brewing, 2019, 125, 53-59.	2.3	2
9	Effect of image degradation on nm-scale MEMS FFT optical displacement measurements. , 2015, , .		1
10	Mechanical Characterization of Individual Brewing Yeast Cells Using Microelectromechanical Systems (MEMS): Cell Rupture Force and Stiffness. Journal of the American Society of Brewing Chemists, 2017, 75, 236-243.	1.1	1
11	Millipixel image correlation for sub nm measurement of MEMS motion. Journal of Micromechanics and Microengineering, 2019, 29, 115013.	2.6	1